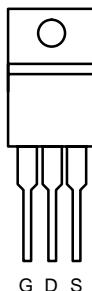


N-Channel 40-V (D-S), 175°C MOSFET

PRODUCT SUMMARY		
$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
40	0.010 @ $V_{GS} = 10$ V	70
	0.014 @ $V_{GS} = 4.5$ V	58

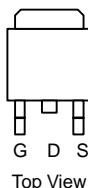
175°C Rated
Maximum Junction Temperature

TO-220AB

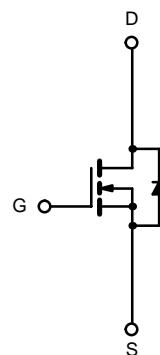


Top View
SUP70N04-10

TO-263



SUB70N04-10



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 175^\circ\text{C}$)	I_D	70	A
$T_C = 100^\circ\text{C}$		47	
Pulsed Drain Current	I_{DM}	140	
Avalanche Current	I_{AR}	60	
Repetitive Avalanche Energy ^a	E_{AR}	180	mJ
Power Dissipation	P_D	107^b	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 175	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient	R_{thJA}	35	40	°C/W
Free Air (TO-220)		45	50	
Junction-to-Case	R_{thJC}	1.2	1.4	

Notes:

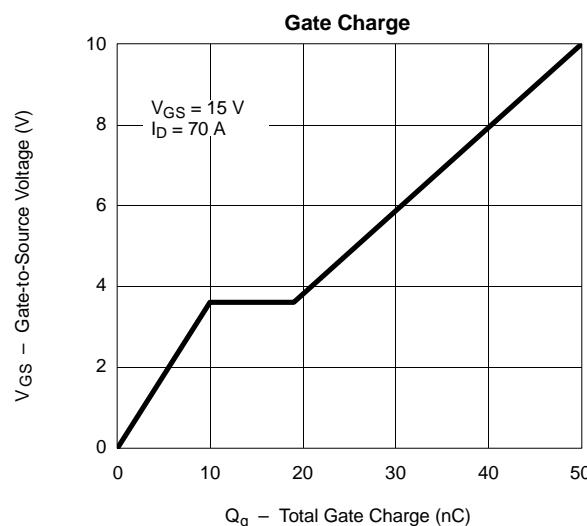
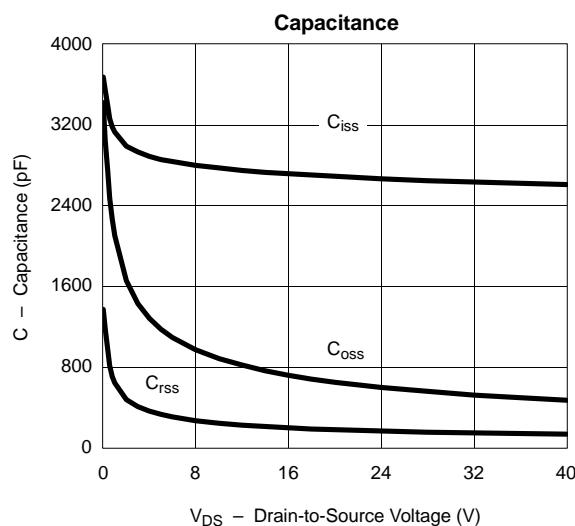
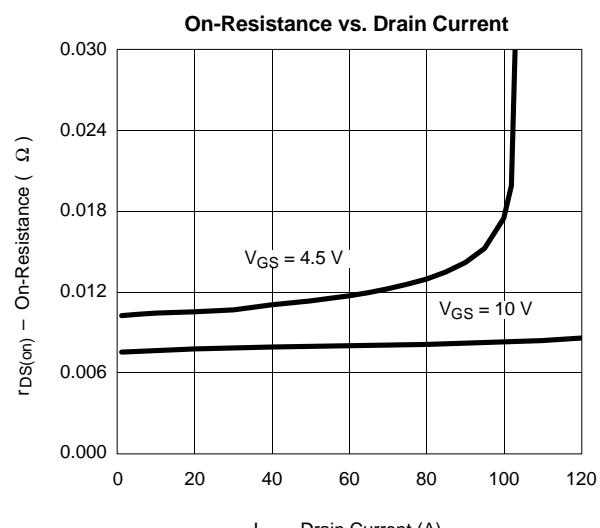
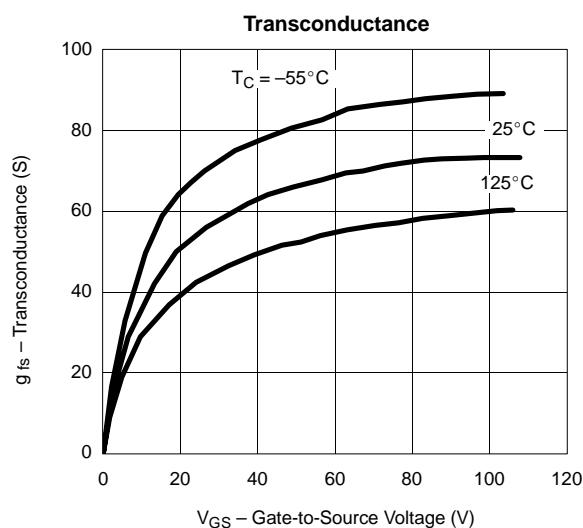
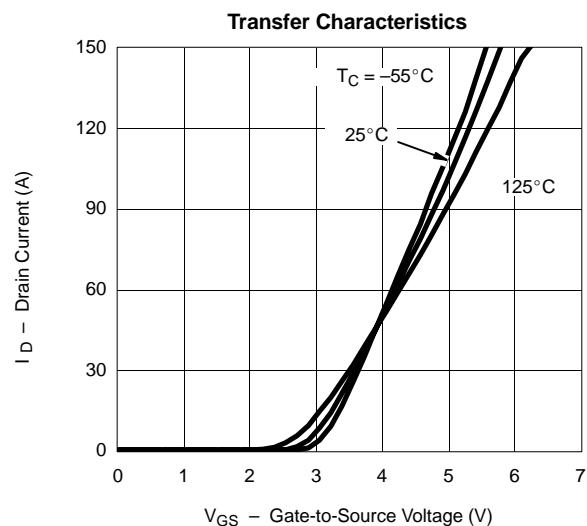
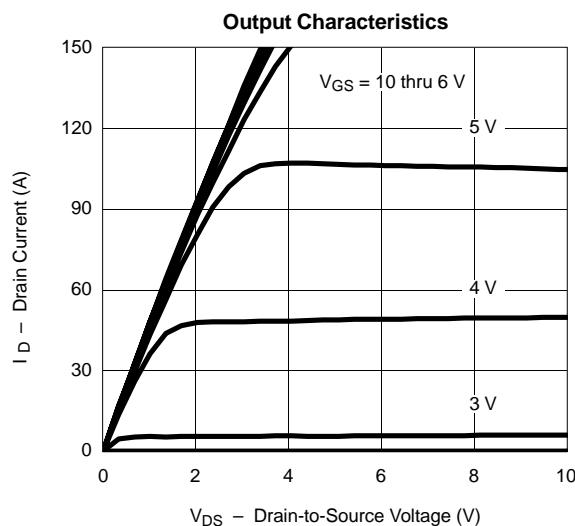
- a. Duty cycle $\leq 1\%$.
- b. See SOA curve for voltage derating.
- c. Surface mounted on 1" FR4 board.

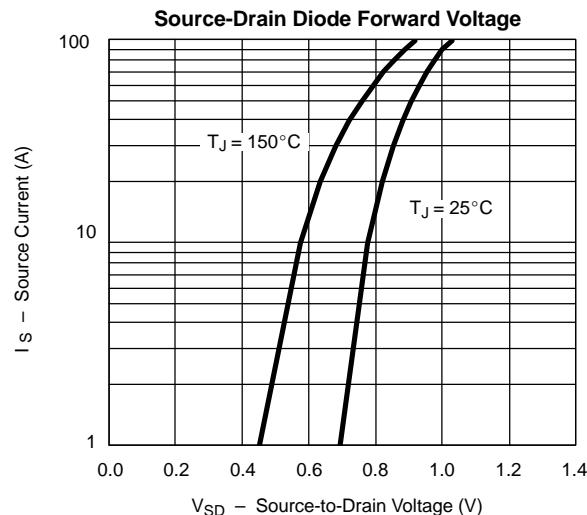
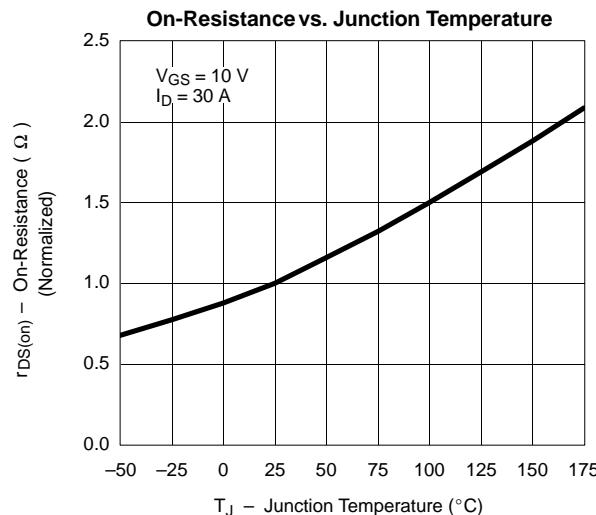
SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1		3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$			1	
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125^\circ\text{C}$			50	
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 175^\circ\text{C}$			150	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	70			A
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$		0.008	0.010	
		$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}, T_J = 125^\circ\text{C}$		0.014	0.017	
		$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}, T_J = 175^\circ\text{C}$		0.0175	0.022	
		$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.011	0.014	
		$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}, T_J = 125^\circ\text{C}$		0.019	0.024	
		$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}, T_J = 175^\circ\text{C}$		0.024	0.031	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}, I_D = 30 \text{ A}$	20	57		s
Dynamic^b						
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		2700		
Output Capacitance	C_{oss}			600		pF
Reversen Transfer Capacitance	C_{rss}			160		
Total Gate Charge ^c	Q_g	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 70 \text{ A}$		50	100	
Gate-Source Charge ^c	Q_{gs}			10		nC
Gate-Drain Charge ^c	Q_{gd}			9		
Turn-On Delay Time ^c	$t_{d(\text{on})}$	$V_{DD} = 15 \text{ V}, R_L = 0.2 \Omega$ $I_D \approx 70 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 2.5 \Omega$		14	30	
Rise Time ^c	t_r			12	30	ns
Turn-Off Delay Time ^c	$t_{d(\text{off})}$			58	100	
Fall Time ^c	t_f			30	60	
Source-Drain Diode Ratings and Characteristics ($T_C = 25^\circ\text{C}$)^b						
Continuous Current	I_s				70	A
Pulsed Current	I_{SM}				140	
Forward Voltage ^a	V_{SD}	$I_F = 70 \text{ A}, V_{GS} = 0 \text{ V}$		1.0	1.5	V
Reverse Recovery Time	t_{rr}	$I_F = 70 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$		50	100	ns

Notes:

- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**THERMAL RATINGS**